Electra House, 32 Southtown Road Great Yarmouth, Norfolk NR31 0DU, England Telephone +44 (0)1493 602602 Email:sales@midasdisplays.com www.midasdisplays.com

| MCOT048064A1V-BI | 48         | 3 x 64           | OLED Module |  |  |  |  |
|------------------|------------|------------------|-------------|--|--|--|--|
| Specification    |            |                  |             |  |  |  |  |
| Version: 1       |            | Date: 27/01/2017 |             |  |  |  |  |
|                  | Revision   |                  |             |  |  |  |  |
| 1                | 25/01/2017 | First            | Issue       |  |  |  |  |

| Display               |                                       |              |                  |
|-----------------------|---------------------------------------|--------------|------------------|
| Resolution            |                                       |              |                  |
| Appearance            | Blue on Black                         |              |                  |
| Logic Voltage         |                                       | <b>POHS</b>  |                  |
| Interface             | I2C                                   | CO           | ompliant         |
| Module Size           | 13.9 <mark>0</mark> x 22.00 x 1.26 mm |              |                  |
| Operating Temperature | -40°C ~ +80°C                         | Box Quantity | Weight / Display |
| Construction          | COT                                   |              |                  |

\* - For full design functionality, please use this specification in conjunction with the SSD1306BZ specification. (Provided Separately)

| Display Accessories |  |  |  |  |  |
|---------------------|--|--|--|--|--|
| Part Number         | Description  |  |  |  |  |
| MPBV4-ISS2          | Direct solder interconnect board. supports 0.7, 0.8, 0.845 and 1mm pitch. Driven from any driver board that can wire 20 a 2mm pitch, 44 way DIL. |  |  |  |  |
|                     |  |  |  |  |  |
|                     |  |  |  |  |  |

| Optional Variants |  |  |  |  |  |
|-------------------|--|--|--|--|--|
| Voltage           |  |  |  |  |  |
|                   |  |  |  |  |  |
|                   |  |  |  |  |  |

# **General Specification**

The Features is described as follow:

■ Dot Matrix: 48 x 64 Dots

■ Module dimension: 13.90× 22.0 × 1.26 mm

Active Area: 10.54×14.70 mm

■ Pixel Size: 0.198 × 0.208mm

■ Pixel Pitch: 0.220 × 0.230 mm

■ Display Mode: Passive Matrix

■ Display Color: Sky blue

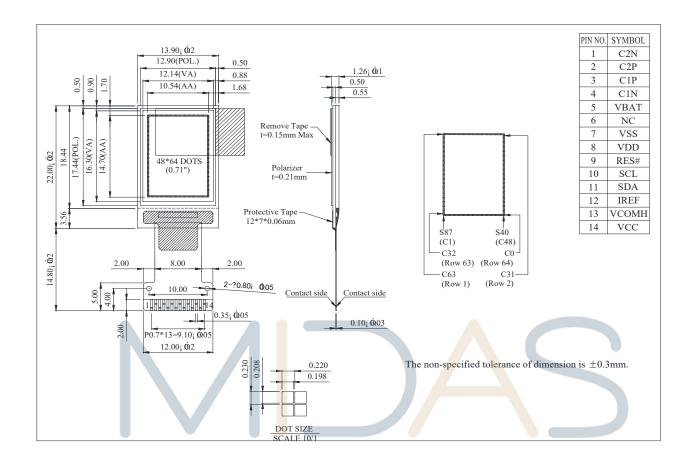
■ Drive Duty: 1/64 Duty

■ IC: SSD1306BZ

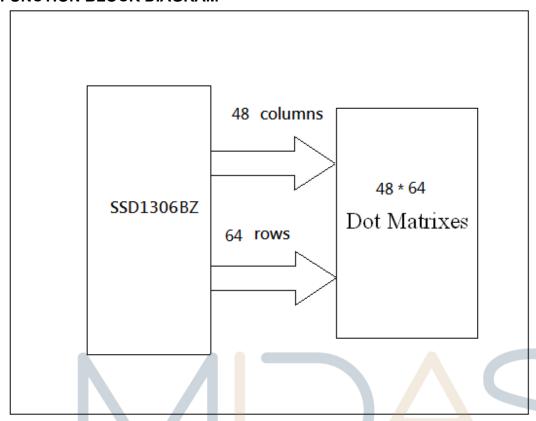
# **Interface Pin Function**

| No. | Symbol | Function   |  |  |  |  |
|-----|--------|--|--|--|--|--|
| 1   | C2N    |  |  |  |  |  |
| 2   | C2P    | Positive Terminal of the Flying Inverting Capacitor Negative Terminal of the   |  |  |  |  |
| 3   | C1P    | Flying Boost Capacitor The charge-pump capacitors are required between   |  |  |  |  |
| 4   | C1N    | e terminals. They must be floated when the converter is not used.  |  |  |  |  |
| 5   | VBAT   | Power Supply for DC/DC Converter Circuit  This is the power supply pin for the internal buffer of the DC/DC voltage converter. It must be connected to external source when the converter is used. It should be connected to VDD when the converter is not used. |  |  |  |  |
| 6   | NC     | No connection.   |  |  |  |  |
| 7   | VSS    | Ground of Logic Circuit This is a ground pin. It acts as a reference for the logic pins. It must be connected to external ground.  |  |  |  |  |
| 8   | VDD    | Power Supply for Logic This is a voltage supply pin. It must be connected to external source.  |  |  |  |  |
| 9   | RES#   | Power Reset for Controller and Driver This pin is reset signal input. When the pin is low, initialization of the chip is executed.   |  |  |  |  |
| 10  | SCL    | Host Data Input/Output Bus   |  |  |  |  |
| 11  |        | When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. When I2C mode is selected, D2 & D1 should be tired together and serve as SDAout & SDAin in application and D0 is the serial clock input SCL.     |  |  |  |  |
| 12  |        | Current Reference for Brightness Adjustment This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current lower than 12.5µA.   |  |  |  |  |
| 13  |        | Voltage Output High Level for COM Signal  This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.   |  |  |  |  |
| 14  | VCC    | Power Supply for OEL Panel This is the most positive voltage supply pin of the chip. A stabilization capacitor should be connected between this pin and VSS when the converter is used. It must be connected to external source when the converter is not used.  |  |  |  |  |

### **Contour Drawing & Block Diagram**



#### **FUNCTION BLOCK DIAGRAM**



<sup>\*</sup>For more information, please refer to Application Note provided by Midas Displays.

### **Absolute Maximum Ratings**

| Parameter                  | Symbol | Min | Max | Unit | Notes |
|----------------------------|--------|-----|-----|------|-------|
| Supply Voltage for Logic   | VDD    | 0   | 4   | V    | 1,2   |
| Supply Voltage for Display | VCC    | 0   | 15  | V    | 1,2   |
| Operating Temperature      | TOP    | -40 | +80 | °C   |       |
| Storage Temperature        | TSTG   | -40 | +80 | °C   | _     |

Note 1: All the above voltages are on the basis of "VSS = 0V".

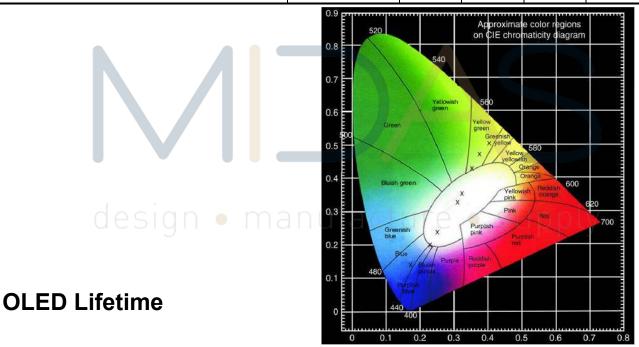
Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate

### **Electrical Characteristics**

| ltem                                 | Symbol | Condition | Min     | Тур  | Max     | Unit     |
|--------------------------------------|--------|-----------|---------|------|---------|----------|
| Supply Voltage for Logic             | VDD    | _         | 2.8     | 3.0  | 3.3     | <b>V</b> |
| Supply Voltage for Display           | VCC    | _         | 7.0     | 7.5  | 7.8     | V        |
| Input High Volt.                     | VIH    | _         | 0.8×VDD | _    | VDDIO   | V        |
| Input Low Volt.                      | VIL    | _         | 0       | _    | 0.2×VDD | V        |
| Output High Volt.                    | VOH    | _         | 0.9×VDD | _    | VDDIO   | V        |
| Output Low Volt.                     | VOL    | _         | 0       | _    | 0.1×VDD | V        |
| 50% Check Board operating<br>Current | ICC    | VCC=7.5V  | _       | 15.0 | 25.0    | mA       |

# **Optical Characteristics**

| Item                     | Symbol    | Condition | Min    | Тур  | Max   | Unit |
|--------------------------|-----------|-----------|--------|------|-------|------|
| View Angle               | (V)θ      | _         | 160    | _    | _     | deg  |
| Niew Aligie              | (Η)φ      | _         | 160    | _    | _     | deg  |
| Contrast Ratio           | CR        | Dark      | 2000:1 | _    | _     | _    |
| Response Time            | T rise    | _         | _      | 10   | _     | μs   |
| Tresponde Time           | T fall    | _         | _      | 10   | _     | μs   |
| Display with 50% check E |           | 60        | 80     | _    | cd/m2 |      |
| CIEx(Sky blue)           | (CIE1931) | 0.12      | 0.16   | 0.20 | _     |      |
| CIEy(Sky blue)           |           | (CIE1931) | 0.22   | 0.26 | 0.30  | _    |



| ITEM                   | Conditions  | Min        | Тур | Remark |
|------------------------|---|------------|-----|--------|
| Operating<br>Life Time | Ta=25℃<br>/ Initial 50% check board<br>brightness Typical Value | 20,000 Hrs | -   | Note   |

#### Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.

# Reliability

**Content of Reliability Test** 

| Environmenta                                | l Test   |  |                        |
|---|--|--|------------------------|
| Test Item                                   | Content of Test  | Test Condition   | Applicable<br>Standard |
| High<br>Temperature<br>storage              | Endurance test applying the high storage temperature for a long time.  | 80°C<br>240hrs   |                        |
| Low<br>Temperature<br>storage               | Endurance test applying the low storage temperature for a long time.   | -40°C<br>240hrs  |                        |
| High<br>Temperature<br>Operation            | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | 80°C<br>240hrs   |                        |
| Low<br>Temperature<br>Operation             | Endurance test applying the electric stress under low temperature for a long time.                                     | -40°C<br>240hrs  |                        |
| High<br>Temperature/<br>Humidity<br>Storage | Endurance test applying the high temperature and high humidity storage for a long time.                                | 60°C,90%RH<br>240hrs   |                        |
| Temperature<br>Cycle                        | Endurance test applying the low and high temperature cycle.  -40°C 25°C 80°C  30min 5min 30min 1 cycle                 | -40°C/80° <mark>C</mark><br>100 cy <mark>cl</mark> es                |                        |
| Mechanical Tes                              | st   |  |                        |
| Vibration test                              | Endurance test applying the vibration during transportation and using.   | 10~22Hz→1.5mmp-p<br>22~500Hz→1.5G<br>Total 0.5hr                     | _suppl                 |
| Shock test                                  | Constructional and mechanical endurance test applying the shock during transportation.                                 | 50G Half sin<br>wave 11 ms<br>3 times of each<br>direction           |                        |
| Atmospheric pressure test                   | Endurance test applying the atmospheric pressure during transportation by air.   | 115mbar<br>40hrs   |                        |
| Others                                      |  |  |                        |
| Static<br>electricity test                  | Endurance test applying the electric stress to the terminal.   | VS=±600V(contact),<br>±800v(air),<br>RS=330Ω<br>CS=150pF<br>10 times |                        |

#### Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

#### **Evaluation criteria**

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

#### **APPENDIX:**

### **RESIDUE IMAGE**

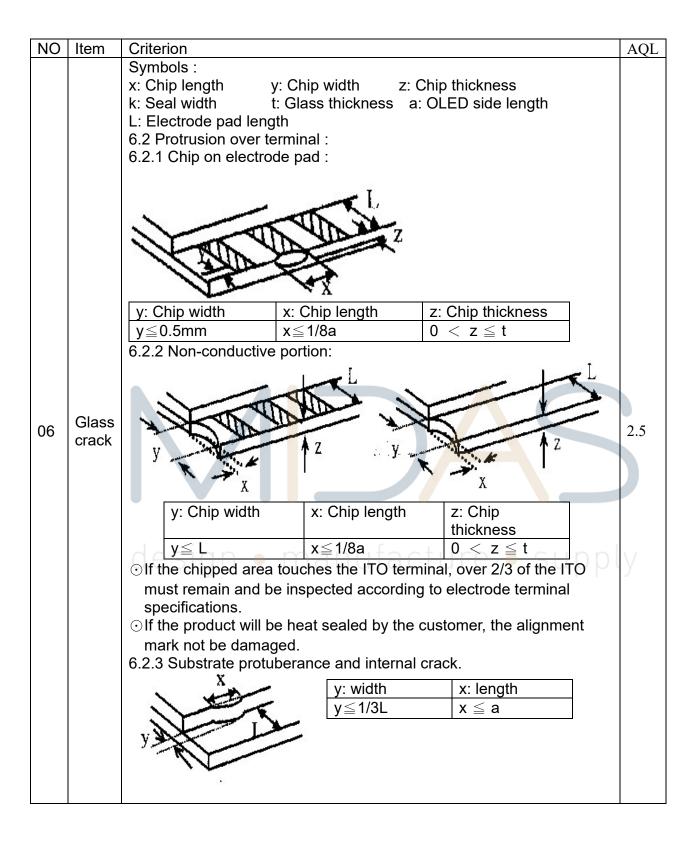
Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



# **Inspection specification**

| NO | Item  | Criterion  |  | AQL |  |  |
|----|---|--|--|-----|--|--|
| 01 | Electrical<br>Testing                                       | <ul> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 OLED viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ul> |  |     |  |  |
| 02 | Black or<br>white<br>spots on<br>OLED<br>(display<br>only)  | three white or black spot  | ts on display ≦0.25mm, no more than<br>ts present.<br>more than two spots or lines within  | 2.5 |  |  |
| 03 | OLED black spots, white spots, contamina tion (non-display) | 3.1 Round type : As following drawing $\Phi = (x + y)/2$   | SIZE Acceptable Q TY $ \Phi \leq 0.10 \qquad \text{Accept no dense} $ $ 0.10 < \qquad \qquad 2 $ $ \Phi \leq 0.20 \qquad \qquad 0.20 < \qquad \qquad 1 $ $ \Phi \leq 0.25 \qquad \qquad 0.25 < \Phi \qquad \qquad 0 $  |     |  |  |
|    |   | 3.2 Line type : (As follow   | ving drawing)  |     |  |  |
|    |   | Length L≤3.0 L≤2.5   |  |     |  |  |
| 04 | Polarizer<br>bubbles  | If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.  | $\begin{array}{c cccc} Size \ \Phi & Acceptable \ Q \ T \\ \hline \ \Phi \leqq 0.20 & Accept \ no \ dense \\ \hline \ 0.20 < \Phi \leqq 0.50 & 3 \\ \hline \ 0.50 < \Phi \leqq 1.00 & 2 \\ \hline \ 1.00 < \Phi & 0 \\ \hline \ Total \ Q \ TY & 3 \\ \end{array}$ |     |  |  |

| NO | Item          | Criterion  | AQL |
|----|---------------|--|-----|
| 05 | Scratches     | Follow NO.3 OLED black spots, white spots, contamination   |     |
|    |               | Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: |     |
|    |               | 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:  |     |
| 06 | Chipped glass |  | 2.5 |
|    | de            | Olf there are 2 or more chips, x is total length of each chip.  6.1.2 Corner crack:  | l.y |
|    |               |  |     |
|    |               | 1/2t < z ≤ 2t Not exceed 1/3k x ≤ 1/8a   |     |
|    |               | ⊙ If there are 2 or more chips, x is the total length of each chip.  |     |



| NO | Item   | Criterion   | AQL   |
|----|--|---|---|
| 07 | Cracked<br>glass   | The OLED with extensive crack is not acceptable.  |   |
| 08 | 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. |   | 0.65<br>2.5<br>0.65                             |
| 09 | Bezel  | <ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>  |   |
| 10 | РСВ. СОВ   | <ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> </ul> | 2.5<br>2.5<br>0.65<br>2.5<br>2.5<br>0.65<br>2.5 |
| 11 | Soldering  | <ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>  | 2.5<br>2.5<br>2.5<br>0.65                       |

| NO | Item                  | Criterion  | AQL  |
|----|-----------------------|--|------|
| 12 | General<br>appearance | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.    | 2.5  |
|    |                       | 12.2 No cracks on interface pin (OLB) of TCP.  | 0.65 |
|    |                       | 12.3 No contamination, solder residue or solder balls on                             | 2.5  |
|    |                       | product.   | 2.5  |
|    |                       | 12.4 The IC on the TCP may not be damaged, circuits.                                 | 2.5  |
|    |                       | 12.5 The uppermost edge of the protective strip on the                               |      |
|    |                       | interface pin must be present or look as if it cause the interface pin to sever.     | 2.5  |
|    |                       | 12.6 The residual rosin or tin oil of soldering (component or                        | 2.5  |
|    |                       | chip component) is not burned into brown or black color.                             | 0.65 |
|    |                       | 12.7 Sealant on top of the ITO circuit has not hardened.                             | 0.65 |
|    |                       | 12.8 Pin type must match type in specification sheet.                                | 0.65 |
|    |                       | 12.9 OLED pin loose or missing pins.   |      |
|    |                       | 12.10 Product packaging must the same as specified on packaging specification sheet. | 0.65 |
|    |                       | 12.11 Product dimension and structure must conform to                                |      |
|    |                       | product specification sheet.   |      |
|    |                       |  |      |

| Check Item   | Classification | Criteria                            |  |
|--|----------------|-------------------------------------|--|
| No Display   | Major          |                                     |  |
| Missing Line                                       | Major          |                                     |  |
| Pixel Short  | Major          |                                     |  |
| Darker Short                                       | Major          |                                     |  |
| Wrong Display                                      | Major          |                                     |  |
| Un-uniform<br>B/A x 100% < 70%<br>A/C x 100% < 70% | Major          | A Normal B Dark Pixel C Light Fixel |  |

### **Precautions in use of OLED Modules**

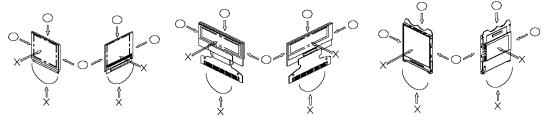
- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) Midas has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)

#### **Handling Precautions**

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- \* Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- \* Water
- \* Ketone
- \* Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- \* Be sure to make human body grounding when handling OLED display modules.
- \* Be sure to ground tools to use or assembly such as soldering irons.
- \* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- \* Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

#### **Storage Precautions**

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Midas Displays. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

### **Designing Precautions**

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.
- (8)The limitation of FPC bending

